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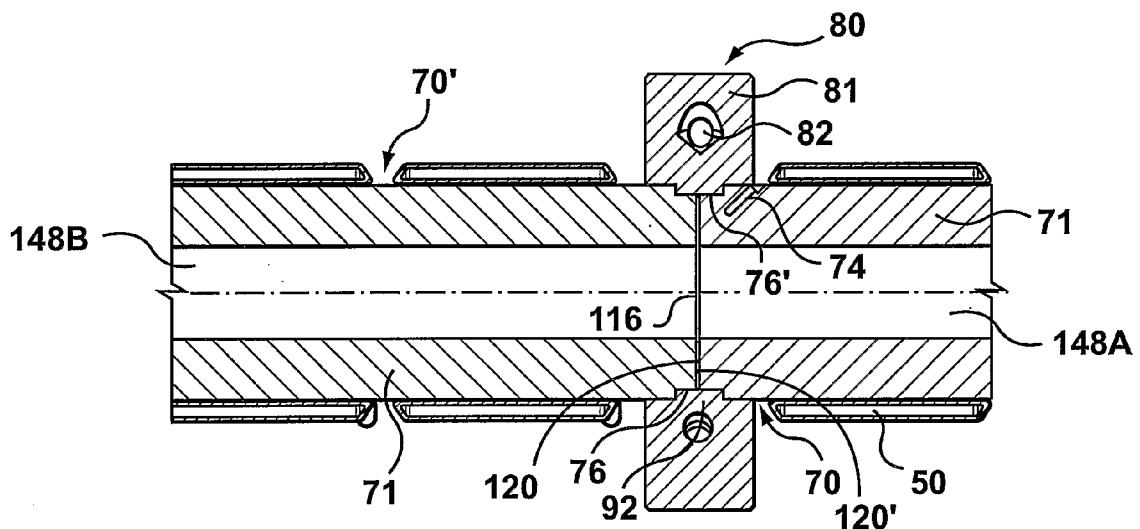
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(54) Title: METHOD AND APPARATUS FOR COUPLING MELT CONDUITS IN A MOLDING SYSTEM AND/OR A RUNNER SYSTEM



(57) Abstract: Method and apparatus for a molding melt conduit and/or runner system includes coupling structure having a first surface configured to couple with a first melt conduit or manifold, and a second surface configured to couple with a second melt conduit or manifold. Cooling structure is configured to provide a coolant to the coupling structure. Preferably, the cooling structure cools the coupling structure to a temperature that causes any melt leaking from near the coupling structure to at least partially solidify thereby further sealing the connection(s).

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